

**KK74HC158A**

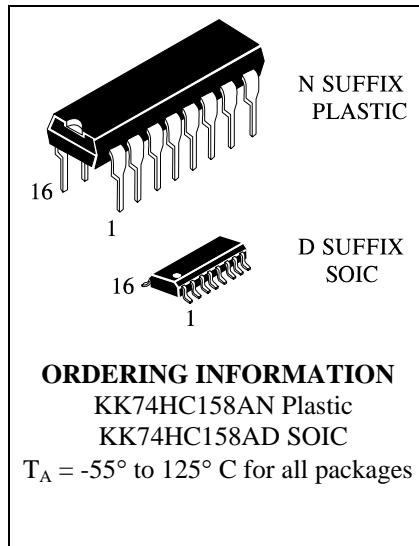
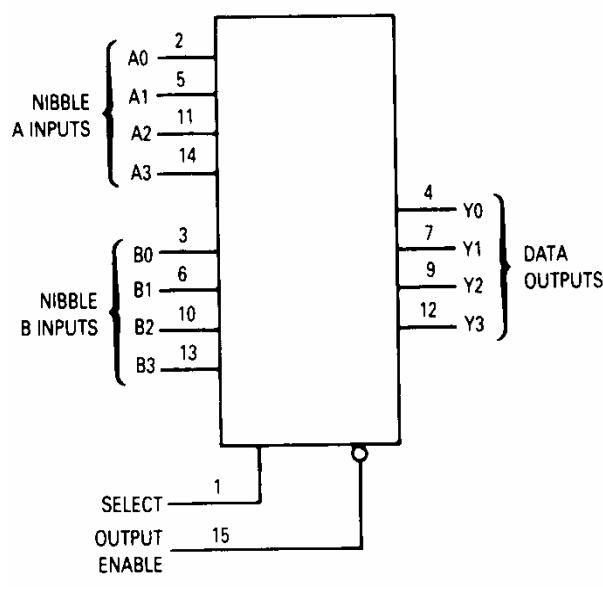
## **Quad 2-Input Data Selectors/Multiplexers**

### **High-Performance Silicon-Gate CMOS**

The KK74HC158A is identical in pinout to the LS/ALS158. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LS/ALSTTL outputs.

This device routes 2 nibbles (A or B) to a single port (Y) as determined by the Select input. The data is presented at the outputs in inverted form. A high level on the Output Enable input sets all four Y outputs to a high level.

- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0  $\mu$ A
- High Noise Immunity Characteristic of CMOS Devices

**LOGIC DIAGRAM****PIN ASSIGNMENT**

SELECT	1 ●	16	V <sub>CC</sub>
A0	2	15	OUTPUT ENABLE
B0	3	14	A3
Y0	4	13	B3
A1	5	12	Y3
B1	6	11	A2
Y1	7	10	B2
GND	8	9	Y2

**FUNCTION TABLE**

Inputs		Outputs
Output Enable	Select	Y0-Y3
H	X	H
L	L	<u>A0-A3</u>
L	H	<u>B0-B3</u>

X=don't care

A0-A3,B0-B3=the levels of the respective Data-Word Inputs

**MAXIMUM RATINGS\***

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage (Referenced to GND)	-1.5 to V <sub>CC</sub> +1.5	V
V <sub>OUT</sub>	DC Output Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>IN</sub>	DC Input Current, per Pin	±20	mA
I <sub>OUT</sub>	DC Output Current, per Pin	±25	mA
I <sub>CC</sub>	DC Supply Current, V <sub>CC</sub> and GND Pins	±50	mA
P <sub>D</sub>	Power Dissipation in Still Air, Plastic DIP+ SOIC Package+	750 500	mW
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
T <sub>L</sub>	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C

\*Maximum Ratings are those values beyond which damage to the device may occur.

Functional operation should be restricted to the Recommended Operating Conditions.

+Derating - Plastic DIP: - 10 mW/°C from 65° to 125°C

SOIC Package: : - 7 mW/°C from 65° to 125°C

**RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V <sub>IN</sub> , V <sub>OUT</sub>	DC Input Voltage, Output Voltage (Referenced to GND)	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature, All Package Types	-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Figure 1) V <sub>CC</sub> =2.0 V V <sub>CC</sub> =4.5 V V <sub>CC</sub> =6.0 V	0 0 0	1000 500 400	ns

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V<sub>IN</sub> and V<sub>OUT</sub> should be constrained to the range GND≤(V<sub>IN</sub> or V<sub>OUT</sub>)≤V<sub>CC</sub>.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V<sub>CC</sub>). Unused outputs must be left open.

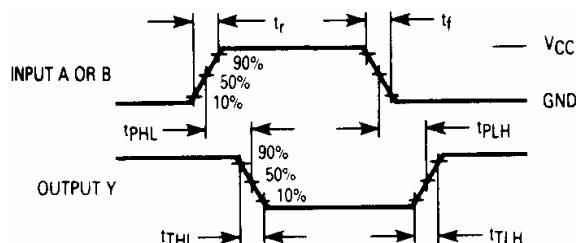
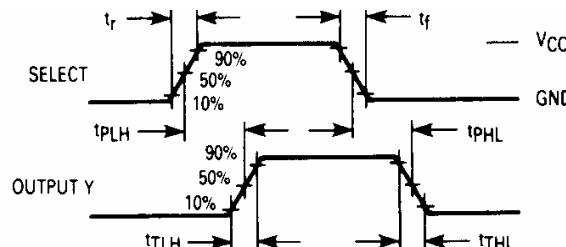
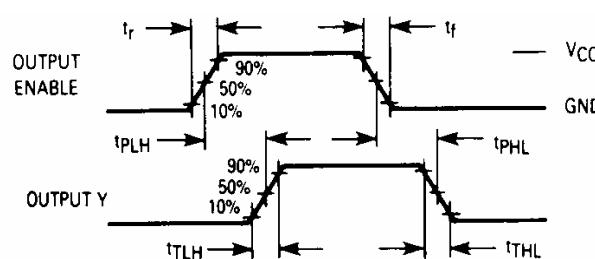
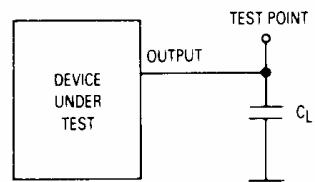
**DC ELECTRICAL CHARACTERISTICS** (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	Guaranteed Limit			Unit
				25 °C to -55°C	≤85 °C	≤125 °C	
V <sub>IH</sub>	Minimum High-Level Input Voltage	V <sub>OUT</sub> =0.1 V or V <sub>CC</sub> -0.1 V   I <sub>OUT</sub>   ≤ 20 μA	2.0 4.5 6.0	1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
V <sub>IL</sub>	Maximum Low - Level Input Voltage	V <sub>OUT</sub> =0.1 V or V <sub>CC</sub> -0.1 V   I <sub>OUT</sub>   ≤ 20 μA	2.0 4.5 6.0	0.5 1.35 1.8	0.5 1.35 1.8	0.5 1.35 1.8	V
V <sub>OH</sub>	Minimum High-Level Output Voltage	V <sub>IN</sub> =V <sub>IH</sub> or V <sub>IL</sub>   I <sub>OUT</sub>   ≤ 20 μA	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		V <sub>IN</sub> =V <sub>IH</sub> or V <sub>IL</sub>   I <sub>OUT</sub>   ≤ 4.0 mA   I <sub>OUT</sub>   ≤ 5.2 mA	4.5 6.0	3.98 5.48	3.84 5.34	3.7 5.2	
V <sub>OL</sub>	Maximum Low-Level Output Voltage	V <sub>IN</sub> =V <sub>IH</sub> or V <sub>IL</sub>   I <sub>OUT</sub>   ≤ 20 μA	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		V <sub>IN</sub> =V <sub>IH</sub> or V <sub>IL</sub>   I <sub>OUT</sub>   ≤ 4.0 mA   I <sub>OUT</sub>   ≤ 5.2 mA	4.5 6.0	0.26 0.26	0.33 0.33	0.4 0.4	
I <sub>IN</sub>	Maximum Input Leakage Current	V <sub>IN</sub> =V <sub>CC</sub> or GND	6.0	±0.1	±1.0	±1.0	μA
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	V <sub>IN</sub> =V <sub>CC</sub> or GND I <sub>OUT</sub> =0μA	6.0	4.0	40	160	μA

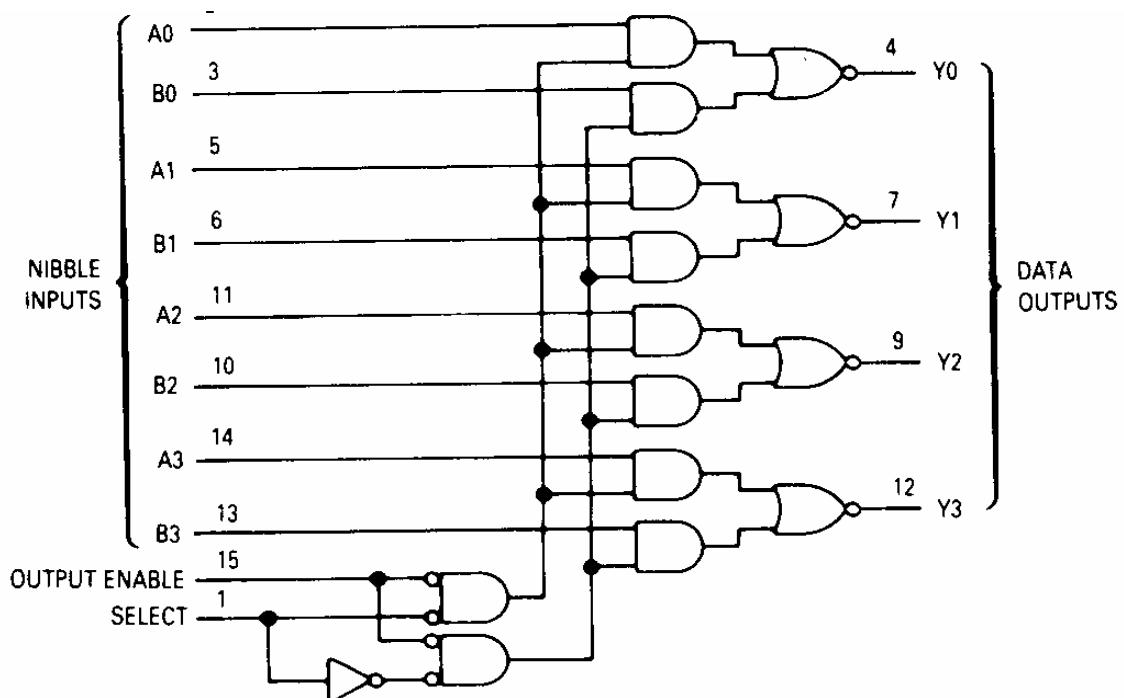
**AC ELECTRICAL CHARACTERISTICS ( $C_L=50\text{pF}$ , Input  $t_r=t_f=6.0\text{ ns}$ )**

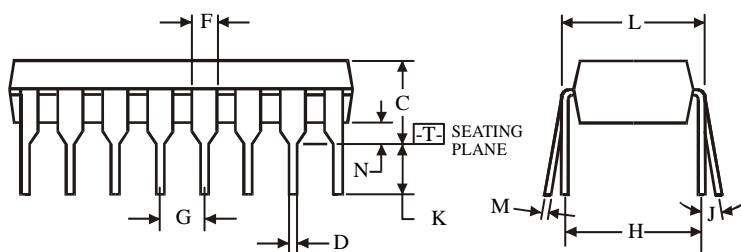
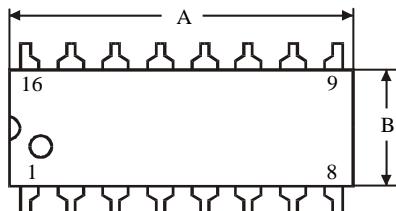
Symbol	Parameter	$V_{CC}$ V	Guaranteed Limit			Unit
			$25^\circ\text{C}$ to $-55^\circ\text{C}$	$\le 85^\circ\text{C}$	$\le 125^\circ\text{C}$	
$t_{PLH}, t_{PHL}$	Maximum Propagation Delay, Input A or B to Output Y (Figures 1 and 4)	2.0 4.5 6.0	105 21 18	130 26 22	160 32 27	ns
$t_{PLH}, t_{PHL}$	Maximum Propagation Delay , Select to Output Y (Figures 2 and 4)	2.0 4.5 6.0	110 22 19	140 28 24	165 33 28	ns
$t_{PLH}, t_{PHL}$	Maximum Propagation Delay , Output Enable to Output Y (Figures 3 and 4)	2.0 4.5 6.0	100 20 17	125 25 21	150 30 26	ns
$t_{TLH}, t_{THL}$	Maximum Output Transition Time, Any Output (Figures 1 and 4)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
$C_{IN}$	Maximum Input Capacitance	-	10	10	10	pF

$C_{PD}$	Power Dissipation Capacitance (Per Package) Used to determine the no-load dynamic power consumption: $P_D=C_{PD}V_{CC}^2f+I_{CC}V_{CC}$	Typical @ $25^\circ\text{C}, V_{CC}=5.0\text{ V}$		$\mu\text{F}$
		33		


**Figure 1. Switching Waveforms**

**Figure 2. Switching Waveforms**

**Figure 3. Switching Waveforms**

\*Includes all probe and jig capacitance.
**Figure 4. Test Circuit**

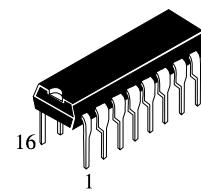
## EXPANDED LOGIC DIAGRAM



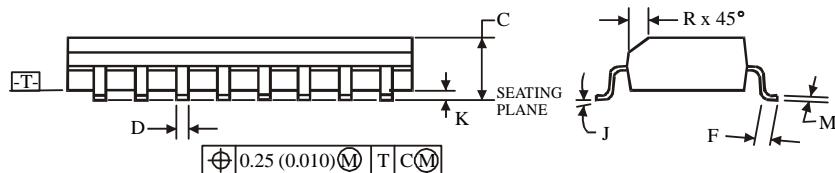
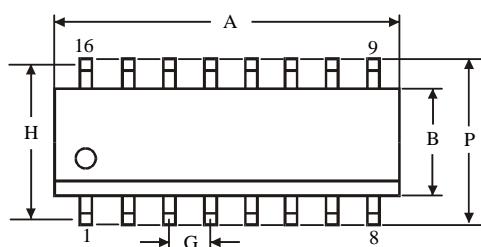
**N SUFFIX PLASTIC DIP  
(MS - 001BB)**

**NOTES:**

1. Dimensions "A", "B" do not include mold flash or protrusions.

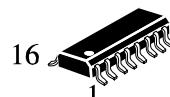
Maximum mold flash or protrusions 0.25 mm (0.010) per side.



Symbol	Dimension, mm	
	MIN	MAX
<b>A</b>	18.67	19.69
<b>B</b>	6.1	7.11
<b>C</b>		5.33
<b>D</b>	0.36	0.56
<b>F</b>	1.14	1.78
<b>G</b>		2.54
<b>H</b>		7.62
<b>J</b>	0°	10°
<b>K</b>	2.92	3.81
<b>L</b>	7.62	8.26
<b>M</b>	0.2	0.36
<b>N</b>	0.38	

**D SUFFIX SOIC  
(MS - 012AC)**

**NOTES:**

1. Dimensions A and B do not include mold flash or protrusion.
2. Maximum mold flash or protrusion 0.15 mm (0.006) per side for A; for B - 0.25 mm (0.010) per side.



Symbol	Dimension, mm	
	MIN	MAX
<b>A</b>	9.8	10
<b>B</b>	3.8	4
<b>C</b>	1.35	1.75
<b>D</b>	0.33	0.51
<b>F</b>	0.4	1.27
<b>G</b>		1.27
<b>H</b>		5.72
<b>J</b>	0°	8°
<b>K</b>	0.1	0.25
<b>M</b>	0.19	0.25
<b>P</b>	5.8	6.2
<b>R</b>	0.25	0.5